

Serial No. 10/054,921

May 4, 2004

Reply to the Office Action dated February 4, 2004

Page 2 of 6

AMENDMENTS TO THE SPECIFICATION:

Please REPLACE the first full paragraph on page 8 of the Specification with the following amended paragraph:

In carrying out frequency adjustment after the packaging process by ion bombardment, a surface acoustic wave element is inserted into a package and is electrically connected through wire bonding or face-down bonding, thereby correcting deviations from the desired frequency in the surface acoustic wave device in the package. At this moment, since this is a different process from the frequency adjustment process conducted after the formation of the IDT, and since it is impossible to use the conventional method, the apparatus of FIG. 3 is preferably used so as to individually adjust the elastic surface acoustic wave device.